

GAL 1733

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TRANSMITTAL FORM <i>(to be used for all correspondence after initial filing)</i>	Application Number	08/916,629
	Filing Date	August 22, 1997
	First Named Inventor	COBBLEY et al.
	Group Art Unit	1733
	Examiner Name	GALLAGHER,
Total Number of Pages in This Submission	Attorney Docket Number	97-0098

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Firm or Individual name	Stephen A. Gratton THE LAW OFFICE OF STEPHEN A. GRATTON
Signature	<i>SGA</i>
Date	February 17, 2000

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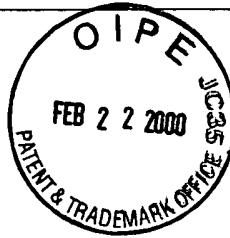
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

CHAD A. COBBLEY
TONGI JIANG
ED A. SCHROCK



Serial No. 08/916,629

Art Unit: 1733

Filing Date: AUGUST 22, 1997

Examiner: GALLAGHER, J.

For: SEMICONDUCTOR DIE ATTACHMENT
METHOD AND APPARATUS

Attorney Docket No. 97-0098

#9/Amend
B.

AMENDMENT
FEBRUARY 17, 2000

Assistant Commissioner of Patents
BOX AMENDMENT (NON FEE)
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Sir:

This is a response to the Office Action dated November 22, 1999 having a statutory period for response set to expire on February 22, 2000. Please amend the captioned case as follows.

In the claims:

Sub 1. (twice amended) A method for [attaching] packaging a semiconductor die to [a leadframe] form a semiconductor package comprising:

providing a leadframe;

providing a cyanoacrylate adhesive material formulated to cure in less than about 60 seconds at a temperature of about 20°C to 30°C and at an ambient atmosphere;

providing a filler in the adhesive material selected to improve a characteristic of the adhesive material in the package;

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